

# SD53

## Low profile shielded power inductors



### Product description

- Octagonal shape utilizes board space
- Shielded drum core
- Inductance range from 1.1 uH to 100 uH
- Current range from 0.44 A to 4.8 A
- 5.7 mm x 5.2 mm footprint surface mount package in a 3.0 mm height
- Ferrite core material
- Halogen free, lead free, RoHS compliant

### Applications

- Desktop computers
- Notebook and laptop regulators
- LED and White LED drivers
- Digital cameras, media devices
- Battery power systems

### Environmental Data

- Storage temperature range (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (Ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D compliant

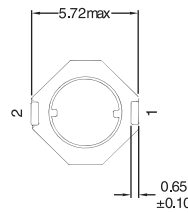
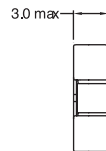
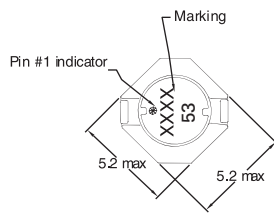


**Product Specifications**

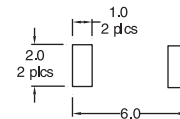
Part Number <sup>5</sup>	OCL1 (µH) ±20%	Part marking	$I_{rms}^2$ (A)	$I_{sat}^3$ (A)	DCR (Ω) typical @ 20 °C	DCR (Ω) maximum @ 20 °C	K-factor <sup>4</sup>
SD53-1R1-R	1.10	A	3.25	4.80	0.017	0.020	48
SD53-2R0-R	2.00	B	2.64	3.30	0.023	0.027	35
SD53-3R3-R	3.30	C	2.26	2.60	0.029	0.034	28
SD53-4R7-R	4.70	D	2.01	2.10	0.039	0.045	21
SD53-6R8-R	6.80	E	1.65	1.85	0.059	0.068	20
SD53-100-R	10.0	F	1.41	1.40	0.077	0.090	15
SD53-150-R	15.0	G	1.10	1.10	0.122	0.142	12
SD53-220-R	22.0	H	0.81	0.94	0.179	0.208	10
SD53-330-R	33.0	I	0.75	0.76	0.221	0.257	8
SD53-470-R	47.0	J	0.64	0.64	0.303	0.352	7
SD53-680-R	68.0	K	0.52	0.58	0.452	0.525	6
SD53-101-R	100	L	0.44	0.45	0.689	0.801	5

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.1 Vrms, 0.0 Adc.
2. Irms: DC current for an approximate ΔT of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125 °C under worst case operating conditions verified in the end application
3. Isat: Peak current for approximately 30% rolloff @ 25 °C.
4. K-factor: Used to determine B p-p for core loss (see graph). B p-p = K\*L\*ΔI, B p-p(mT), K: (K factor from table), L: (Inductance in uH), ΔI (Peak to peak ripple current in Amps).
5. Part Number Definition: SD53-xxx-R  
SD53 = Product code and size; -xxx = Inductance value in uH; R = decimal point; If no R is present then third character equals the number of zeros.  
-R suffix = RoHS compliant.

**Dimensions (mm)**



RECOMMENDED PCB LAYOUT

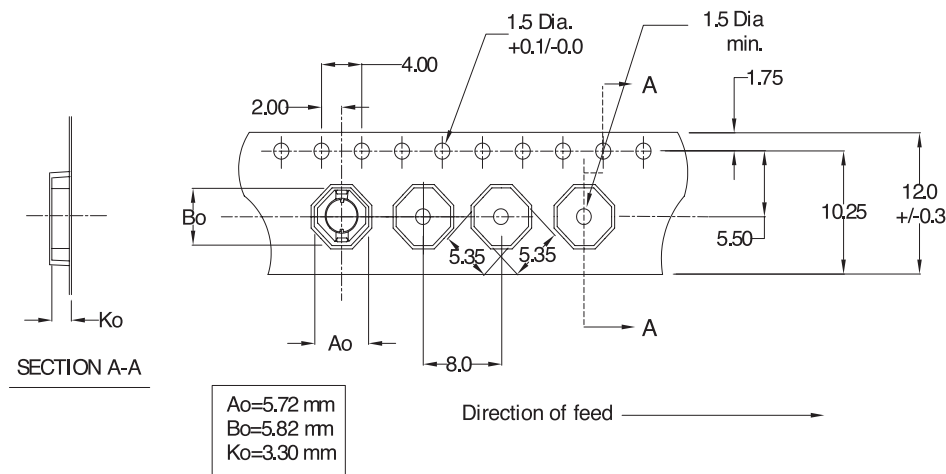


Part Marking: Line 1: (1st digit= inductance value per Part Marking Designator); (2nd digit= Bi-weekly production date code); (3rd digit= Last digit of the year produced), (4th digit= Internal manufacturing code). Line 2: 53=product size code)

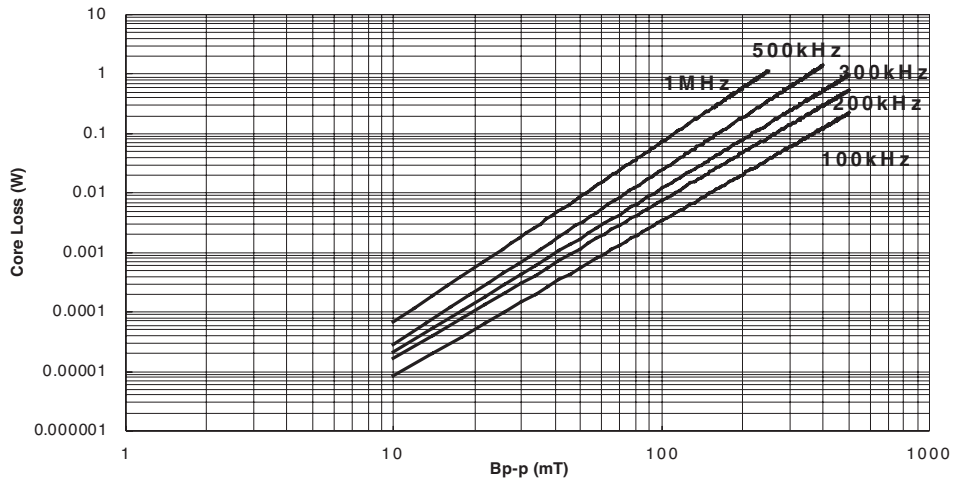
Do not route traces or vias underneath the inductor

**Packaging information (mm)**

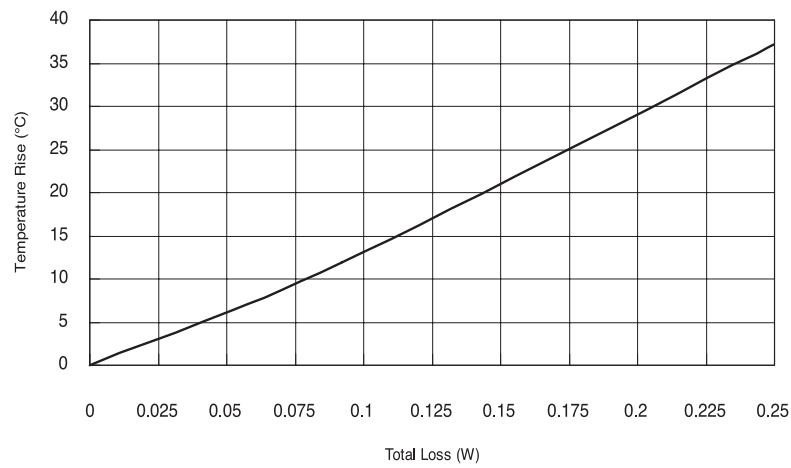
Parts packaged on 13" diameter reel, 2,600 parts per reel.



Core loss vs. Bp-p

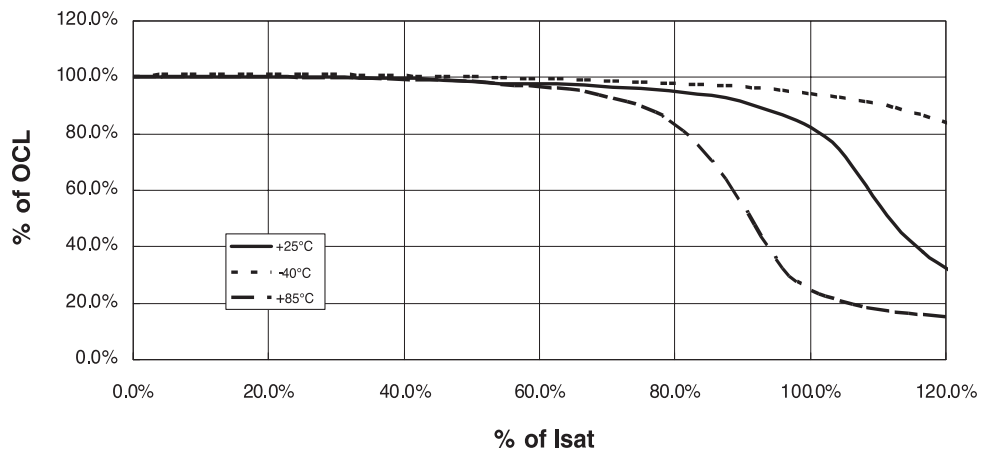


Temperature rise vs. total loss



Inductance characteristics

OCL vs. Isat



**Solder reflow profile**



**Table 1 - Standard SnPb Solder ( $T_C$ )**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

**Table 2 - Lead (Pb) Free Solder ( $T_C$ )**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

**Reference JDEC J-STD-020D**

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. ( $T_{smin}$ )	100°C	150°C
• Temperature max. ( $T_{smax}$ )	150°C	200°C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_P$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at liquidous ( $t_L$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_P$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_C$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_P$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

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